

ANHE520SR InSb Hall Element

- Ultra High-sensitivity InSb Hall element
- Classic SOT Package
- Shipped in packet-tape reel (3000pcs per reel)

Absolute Maximum Rating

| Item | Symbol | Conditions | Limit | Unit |
|-----------------------------|------------|--------------------------|------------|------|
| Operating Temperature Range | T_{opr} | | -40 ~ +125 | °C |
| Storage Temperature Range | T_{STG} | | -55 ~ +150 | °C |
| Maximum Input Current | I_{cmax} | $T_a = 25^\circ\text{C}$ | 20 | mA |
| Maximum Input Voltage | V_{cmax} | $T_a = 25^\circ\text{C}$ | 2 | V |

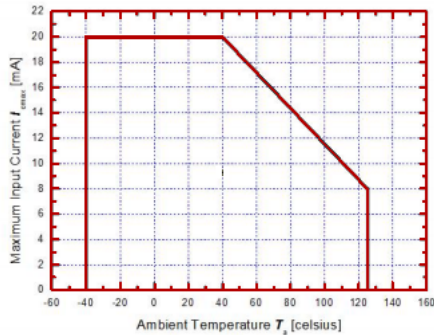


Figure 1. 1 Maximum input current I_{cmax}

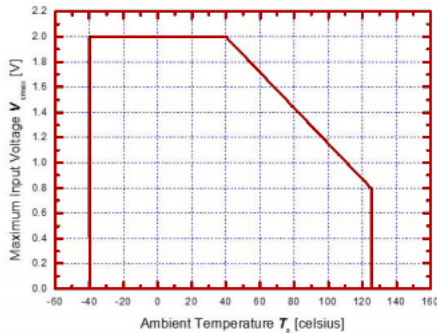
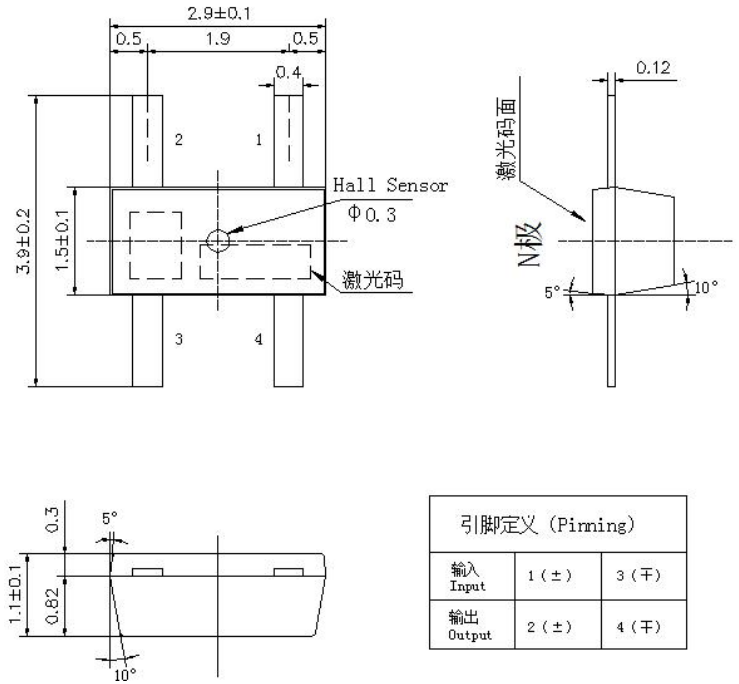


Figure 1. 2 Maximum input Voltage V_{cmax}

Dimensional Drawing (Unit: mm)



Electrical Characteristics (RT=25°C)

Table 1. Electrical Characteristics of ANHE520SR

| Item | Symbol | Test Condi. | Min. | Typ. | Max. | Unit |
|---------------------------|-----------------|--|------|------|------|------------|
| Hall Voltage | V_H | $B = 50\text{mT}$, $V_C = 1\text{V}$ $T_a = RT$ | 168 | | 516 | mV |
| Input Resistance | R_{in} | $B = 0\text{mT}$, $I_C = 0.1\text{mA}$ $T_a = RT$ | 240 | | 550 | Ω |
| Output Resistance | R_{out} | $B = 0\text{mT}$, $I_C = 0.1\text{mA}$ $T_a = RT$ | 240 | | 550 | Ω |
| Offset Voltage | V_{os} | $B = 0\text{mT}$, $V_C = 1\text{V}$ $T_a = RT$ | -5 | | +5 | mV |
| Temp. Coeffi. of V_H | αV_H | $B = 50\text{mT}$, $I_C = 5\text{mA}$, $T_a = 0^\circ\text{C} \sim 40^\circ\text{C}$ | | -1.8 | | %/°C |
| Temp. Coeffi. of R_{in} | αR_{in} | $B = 0\text{mT}$, $I_C = 0.1\text{mA}$, $T_a = 0^\circ\text{C} \sim 40^\circ\text{C}$ | | -1.8 | | %/°C |
| Dielectric strength | | 100V D.C | 1.0 | | | M Ω |

Note:

$$1. \quad V_H = V_{H-M} - V_{os}$$

In which V_{H-M} is the Output Hall Voltage, V_H is the Hall Voltage and V_{os} is the offset voltage under the identical electrical stimuli.

$$2. \quad \alpha V_H = \frac{1}{V_H(T_1)} \times \frac{V_H(T_3) - V_H(T_2)}{(T_3 - T_2)} \times 100$$

$$3. \quad \alpha R_{in} = \frac{1}{R_{in}(T_1)} \times \frac{R_{in}(T_3) - R_{in}(T_2)}{(T_3 - T_2)} \times 100 \quad T_1 = 20^\circ\text{C}, T_2 = 0^\circ\text{C}, T_3 = 40^\circ\text{C}$$

Classification of Output Hall Voltage (V_H)

Table 2. Classification of Hall Voltage

| Rank | V_H [mV] | Conditions |
|------|------------|------------------|
| C | 168 ~ 204 | B=50mT, $V_C=1V$ |
| D | 196 ~ 236 | |
| E | 228 ~ 274 | |
| F | 266 ~ 320 | |
| G | 310 ~ 370 | |
| H | 360 ~ 415 | |
| I | 405 ~ 465 | |
| J | 454 ~ 516 | |

Characteristic Curves

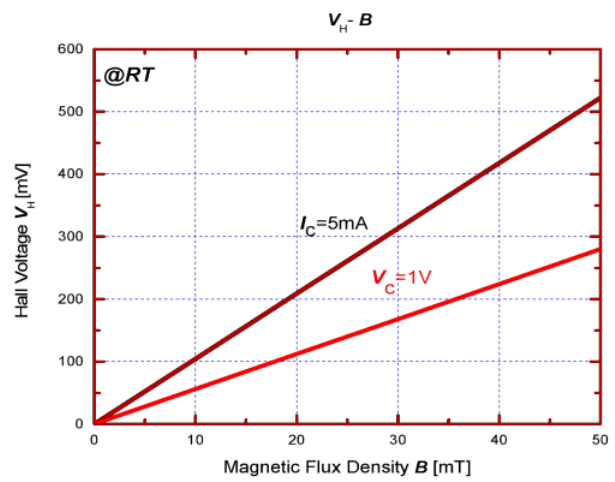
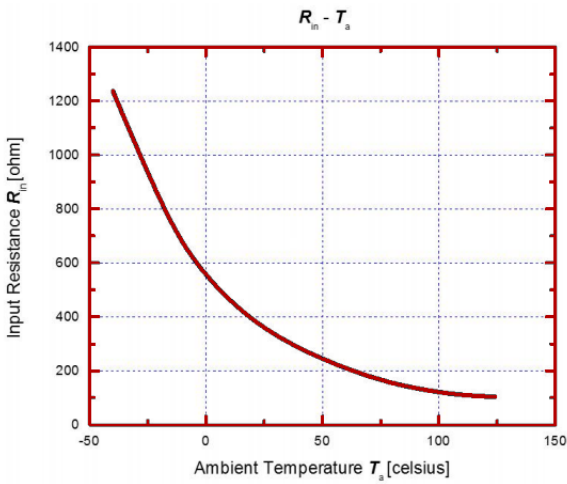


Figure 2. Input resistance R_{in} as a function of ambient temperature T_a .

Figure 3. Hall voltage V_H as a function of magnetic flux density B .

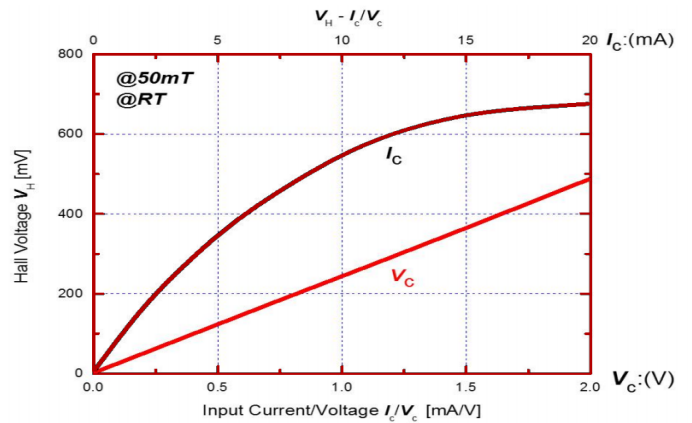
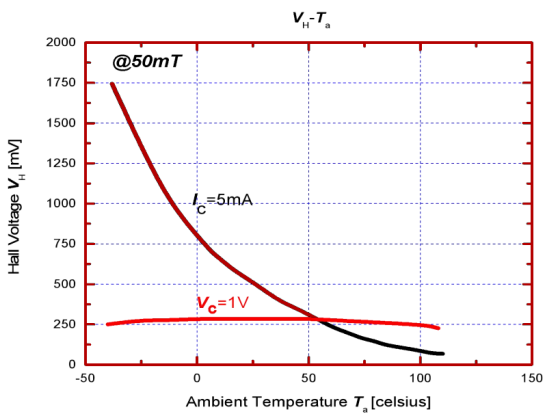


Figure 4. Hall voltage V_H as a function of ambient temperature T_a .

Figure 5. Hall voltage V_H as a function of electrical stimuli I_C/V_C .

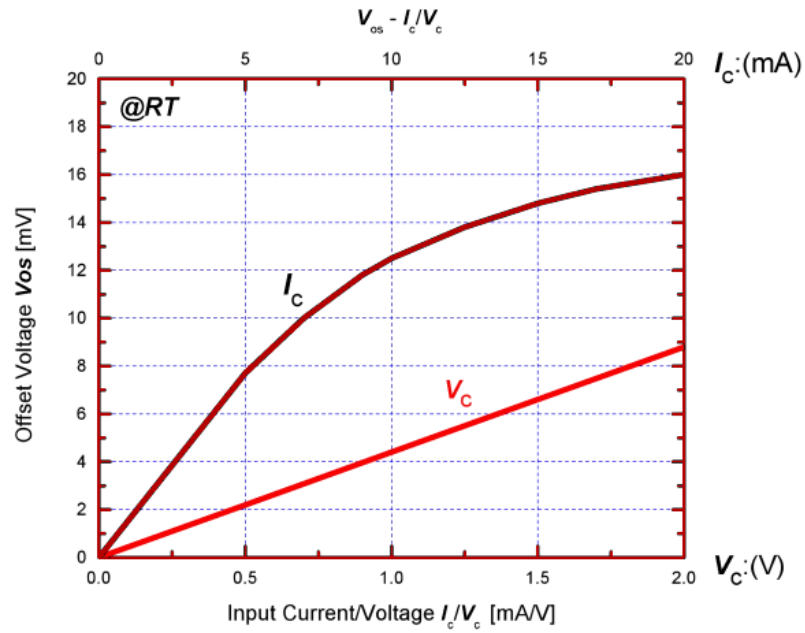


Figure 6. Offset voltage V_{os} as a function of electrical stimuli I_c / V_c .

Reliability Test Terms

Table 2. Reliability Test Terms, Conditions and Duration.

| No. | Terms | Conditions | Duration |
|-----|-----------------------------------|---|-----------|
| 1 | High Temperature Storage (HTS) | 【JEITA EIAJ ED-4701】 $T_a = 150 (0 \sim +10) \text{ }^\circ\text{C}$ | 1000 hrs |
| 2 | Heat Cycle (HC) | 【JEITA EIAJ ED-4701】 $T_a = -55 \text{ }^\circ\text{C} \sim 150 \text{ }^\circ\text{C}$ high temp. - normal temp. - low temp. 30 min - 5 min - 30 min | 30 cycles |
| 3 | Temp. Humidity Storage (THS) | 【JEITA EIAJ ED-4701】 $T_a = 85 \pm 3 \text{ }^\circ\text{C}$, $R_h = 85 \pm 5 \%$ | 1000 hrs |
| 4 | Reflow Soldering (RS) | 【JEITA EIAJ ED-4701】 $260 \pm 5 \text{ }^\circ\text{C}$ | 10 sec |
| 5 | High Temp. Operating (HTO) | $T_a = 125 \text{ }^\circ\text{C}$, $V_c = 1\text{V}$ | 1000 hrs |

Criteria:

- Variation of Hall Voltage V_H and input/output resistances $R_{in/out}$ are less than 20%.
- Variation of offset voltage V_{os} is less than $\pm 16\text{mV}$.
- Other parameters in **Table 1.** are still within their ranges stated in **Table 1.**

Soldering Conditions

The following conditions should be preserved. Solder ability should be checked by yourself, because it is depend on solder paste material and other parameters.

Material of solder flux

- Use the resin based flux and refrain from using organic or inorganic acid based and water-soluble one.

Cleansing of solder flux conditions

- Use Ethanol or Isopropyl alcohol as cleansing material.
- Process temperature should be 50 °C or less.
- Duration should be 5 minutes or less.

Hand soldering conditions

- Apart from the mold resin more than 1mm.
- Solder at temperature 300 °C for less than 5s.

Wave soldering conditions

- Temperature in Pre-heating zone should be lower than 150°C.
- Temperature in Soldering zone should be lower than 270°C.

Precautions for ESD

This product is the device that is sensitive to ESD (Electrostatic Discharge). Handling Hall Elements with the ESD-Caution mark under the environment in which

- Static electrical charge is unlikely to arise (Ex: Relative Humidity over 40%RH).
- Wearing the anti-static suit and wristband when handling the devices.
- Implementing measures against ESD as for containers that directly touch the devices.

Precautions for Storage

- Products should be stored at an appropriate temperature and humidity (5° C to 35° C, 40%RH to 60%RH) after the unsealing of the MBB. Keeping products away from chlorine and corrosive gas.
- **For storage longer than 2 years**
Products are sealed in MBB with a desiccant. It is recommended to store in nitrogen atmosphere with MBB sealed. Oxygen and H₂O of atmosphere oxidizes leads of products and lead solder ability get worse.

Precautions for Safety

- Do not alter the form of this product into a gas, powder or liquid through burning, crushing or chemical processing.
- Observe laws and company regulations when discarding this product.